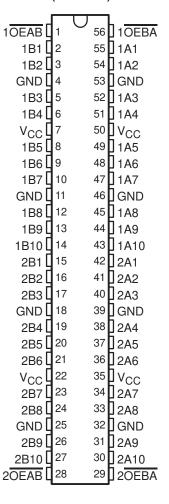
SCAS197B - JUNE 1990 - REVISED NOVEMBER 1996

- **Members of the Texas Instruments** Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes **PCB Layout**
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- **Package Options Include Shrink Plastic** Small-Outline 300-mil (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center **Pin Spacings**

description

The 'ACT16861 are noninverting 20-bit transceivers designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

The 'ACT16861 can be used as two 10-bit transceivers or one 20-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the output-enable (\overline{OEAB} or \overline{OEBA}) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively **54ACT16861...WD PACKAGE 74ACT16861...DL PACKAGE** (TOP VIEW)



The 74ACT16861 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16861 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16861 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

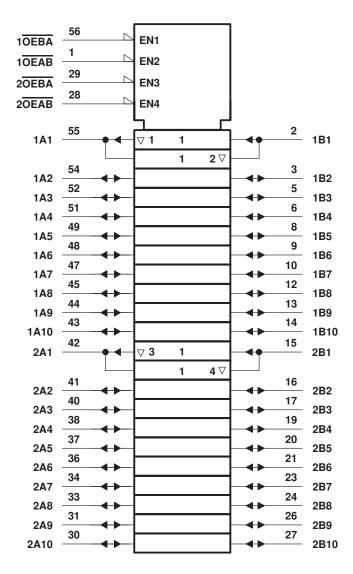
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FUNCTION TABLE (each 10-bit section)

`						
INP	UTS	OPERATION				
OEAB	OEBA	OPERATION				
L	L	Latch A and B (A = B)				
L	Н	A to B				
Н	L	B to A				
Н	Н	Isolation				

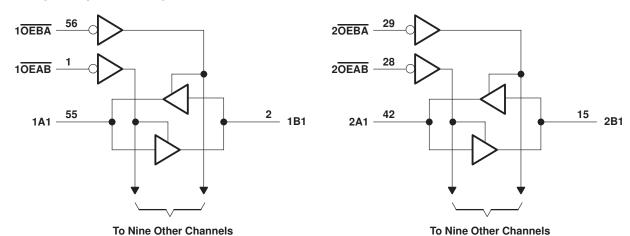
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)–C	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)—C	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±500 mA
Maximum power package dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 3)

		54	ACT1686	61	74	61	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		zh.	2			V
V _{IL}	Low-level input voltage		S.	0.8			0.8	V
VI	Input voltage	0	Q	VCC	0		VCC	V
VO	Output voltage	0	C	VCC	0		VCC	V
loh	High-level output current	\(\lambda\)	20	-24			-24	mA
loL	Low-level output current	D'AZ	,	24			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

54ACT16861, 74ACT16861 20-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	RAMETER	TEST CONDITIONS	Vaa	T,	Δ = 25°C	;	54ACT	16861	74ACT	16861	UNIT
PAI	NAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		10.1 FO.11A	4.5 V	4.4			4.4		4.4		
		ΙΟΗ = -50 μΑ	5.5 V	5.4			5.4		5.4		1 1
VOH		1011 24 mA	4.5 V	3.94			3.8		3.8		V
		I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8		
		I _{OH} = -75 mA [†]	5.5 V				3.85		3.85		
		I _{OL} = 50 μA				0.1		0.1		0.1	
		ΙΟΣ = 30 μΑ	5.5 V			0.1		0.1		0.1	
VOL		10. 24 mA	4.5 V			0.36		0.44		0.44	V
		I _{OL} = 24 mA	5.5 V			0.36	,	0.44		0.44	
		I _{OL} = 75 mA [†]	5.5 V				05	1.65		1.65	
II	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1	90	±1		±1	μΑ
loz‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5	Ya	±5		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
ΔI _{CC} §	One input at 3.4 V, Other inputs at V _{CC} or G		5.5 V			0.9		1		1	mA
Ci	Control inputs	V _I = V _{CC} or GND	5 V		4.5						pF
C _{io}	A or B ports	V _O = V _{CC} or GND	5 V		17						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	ղ = 25°C	;	54ACT	16861	74ACT	16861	UNIT
PANAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
[†] PLH	A or B	B or A	3.1	6.5	9.2	3.1	10.4	3.1	10.4	ns
^t PHL	AOIB		2.9	7.5	10	2.9	C11.1	2.9	11.1	115
^t PZH	OFDA - OFAD	A or B	2.4	6.6	9	2.4	10	2.4	10	ns
[†] PZL	OEBA or OEAB		3.7	8.5	11.5	3.7	12.7	3.7	12.7	
[†] PHZ	OFPA - OFAB	A - :: D	4.9	7.4	9.8	4.9	10.7	4.9	10.7	no
[†] PLZ	OEBA or OEAB	A or B	4.5	6.9	9.3	4.5	10	4.5	10	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

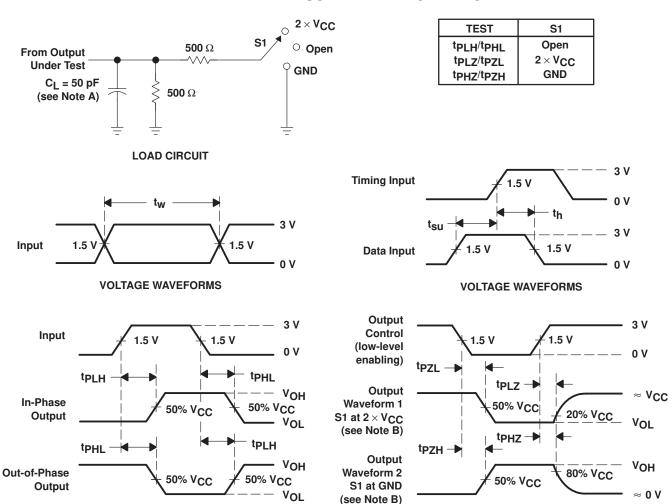
	PARAMETER	TEST CO	TYP	UNIT		
C _{pd}	Power dissination appealtance per transcriver	Outputs enabled	C. 50 pE	f = 1 MHz	64	nE.
	Power dissipation capacitance per transceiver	Outputs disabled	C _L = 50 pF,	t = 1 MHz	14	p⊦

 $[\]mbox{\ensuremath{^{\ddagger}}}\mbox{ For I/O ports, the parameter I}_{\mbox{OZ}}\mbox{ includes the input leakage current.}$

[§] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

VOLTAGE WAVEFORMS

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

VOLTAGE WAVEFORMS

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f = 3~ns$, $t_f = 3~ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74ACT16861DL	LIFEBUY	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16861	
74ACT16861DLR	ACTIVE	SSOP	DL	56	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16861	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

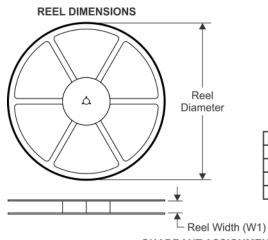
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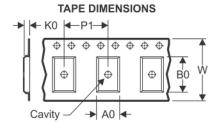
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

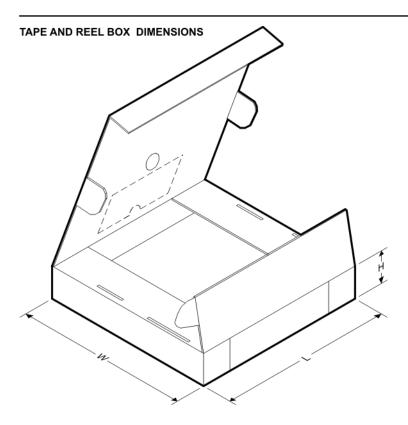
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16861DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16861DLR	SSOP	DL	56	1000	367.0	367.0	55.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT16861DL	DL	SSOP	56	20	473.7	14.24	5110	7.87

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